



## Product Change Notification: NTD0-09AEDU529

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### Date:

12-Sep-2025

### Product Category:

Memory

### Notification Subject:

CCB 7727 Initial Notice: Qualification of MMT as an additional assembly site for SST25WF080BT-40I/NP, SST25WF040BT-40E/NP, SST25WF040BT-40I/NP, SST25WF080BT-40E/NP13GVAO, SST25WF080BT-40E/NP and SST25WF040BT-40E/NP13GVAO catalog part numbers (CPN) in 8L UDFN (2x3x0.55mm) package.

### Affected CPNs:

[NTD0-09AEDU529\\_Affected\\_CPN\\_09122025.pdf](#)

[NTD0-09AEDU529\\_Affected\\_CPN\\_09122025.csv](#)

**PCN Status:** Initial Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of MMT as an additional assembly site for SST25WF080BT-40I/NP, SST25WF040BT-40E/NP, SST25WF040BT-40I/NP, SST25WF080BT-40E/NP13GVAO, SST25WF080BT-40E/NP and SST25WF040BT-40E/NP13GVAO catalog part numbers (CPN) in 8L UDFN (2x3x0.55mm) package.

### Pre and Post Summary Changes:

|            | Pre Change                          | Post Change                         |                                                    |
|------------|-------------------------------------|-------------------------------------|----------------------------------------------------|
| Assessment | UTAC Thai Limited (UTL-1)<br>(NSEB) | UTAC Thai Limited (UTL-1)<br>(NSEB) | Microchip Technology Thailand<br>(Branch)<br>(MMT) |

|                                                                                   |         |         |            |
|-----------------------------------------------------------------------------------|---------|---------|------------|
| b<br>l<br>y<br><br>S<br>i<br>t<br>e                                               |         |         |            |
| W<br>i<br>r<br>e<br>M<br>a<br>t<br>e<br>r<br>i<br>a<br>l                          | Au      | Au      | Au         |
| D<br>i<br>e<br>A<br>t<br>t<br>a<br>c<br>h<br>M<br>a<br>t<br>e<br>r<br>i<br>a<br>l | HR-5104 | HR-5104 | ATB F125E* |
| M<br>o<br>l<br>d<br>i<br>n<br>g<br>C                                              | G700LTD | G700LTD | G700LTD    |

|                     |           |           |           |
|---------------------|-----------|-----------|-----------|
| Compound Material   |           |           |           |
| Lead-Frame Material | EFTEC-64T | EFTEC-64T | EFTEC-64T |

*\*PFAS free material*

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve on-time delivery performance by qualifying MMT as an additional assembly site.

**Change Implementation Status:** In Progress

**Estimated Qualification Completion Date:** October 2025

**Note:** Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Timetable Summary:**

|                          | September 2025 |    |    |    |    | October 2025 |    |    |    |
|--------------------------|----------------|----|----|----|----|--------------|----|----|----|
| Work Week                | 36             | 37 | 38 | 39 | 40 | 41           | 42 | 43 | 44 |
| Initial PCN Issue Date   |                | x  |    |    |    |              |    |    |    |
| Qual Report Availability |                |    |    |    |    |              |    |    | x  |
| Final PCN Issue Date     |                |    |    |    |    |              |    |    | x  |

**Method to Identify Change:** Traceability Code

**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:** September 12, 2025: Issued initial notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

**Attachments:**

**PCN\_NTDO-09AEDU529\_Qual Plan.pdf**  
**PFAS Elimination and Die Attach\_Explanation.pdf**

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

SST25WF080BT-40I/NP

SST25WF040BT-40E/NP

SST25WF040BT-40I/NP

SST25WF080BT-40E/NP13GVAO

SST25WF080BT-40E/NP

SST25WF040BT-40E/NP13GVAO



**MICROCHIP**

## **QUALIFICATION PLAN SUMMARY**

**PCN #: NTDO-09AEDU529**

**Date:**

**August 28, 2025**

**Qualification of MMT as an additional assembly site for SST25WF080BT-40I/NP, SST25WF040BT-40E/NP, SST25WF040BT-40I/NP, SST25WF080BT-40E/NP13GVAO, SST25WF080BT-40E/NP and SST25WF040BT-40E/NP13GVAO catalog part numbers (CPN) in 8L UDFN (2x3x0.55mm) package.**

Purpose: Qualification of MMT as an additional assembly site for SST25WF080BT-40I/NP, SST25WF040BT-40E/NP, SST25WF040BT-40I/NP, SST25WF080BT-40E/NP13GVAO, SST25WF080BT-40E/NP and SST25WF040BT-40E/NP13GVAO catalog part numbers (CPN) in 8L UDFN (2x3x0.55mm) package.

CCB No. 7727

|                   |                                          |                           |
|-------------------|------------------------------------------|---------------------------|
| <u>Misc.</u>      | Assembly site                            | MMT                       |
|                   | BD Number                                | BD-003276-01              |
|                   | MP Code (MPC)                            | X0502YPRXVA1              |
|                   | Part Number (CPN)                        | SST25WF080BT-40E/NP13GVAO |
|                   | MSL information                          | MSL1                      |
|                   | Assembly Shipping Media (T/R, Tube/Tray) | T/R                       |
|                   | Base Quantity Multiple (BQM)             | 3000                      |
|                   | Reliability Site                         | MTAI                      |
| <u>Lead-Frame</u> | Paddle size                              | Chip on Lead design       |
|                   | Material                                 | EFTEC-64T                 |
|                   | DAP Surface Prep                         | Ag on lead only           |
|                   | Treatment                                | Roughened                 |
|                   | Process                                  | Etched                    |
|                   | Lead-lock                                | No                        |
|                   | Part Number                              | 10100875                  |
|                   | Lead Plating                             | Matte tin                 |
| <u>Bond Wire</u>  | Material                                 | Au                        |
| <u>Die Attach</u> | Part Number                              | ATB F125E                 |
|                   | Conductive                               | No                        |
| <u>MC</u>         | Part Number                              | G700LTD                   |
| <u>PKG</u>        | Package Type                             | UDFN                      |
|                   | Pin/Ball Count                           | 8                         |
|                   | PKG width/size                           | 2x3                       |

| Test Name                                            | Conditions                                                                                                                                                                                            | Reliability Stress Read Point<br>Grade 1: -40°C to +125°C (MCHP E Temp) | Pre & Post Reliability Stress Test Temperature<br>Grade 1: -40°C to +125°C (MCHP E Temp) | Sample Size                                               | Min. Qty of Spares per Lot (should be properly marked) | Qty of Lots | Total Units | Fail Accept Qty  | Est. Dur. Days | Special Instructions                                                                                                                                                                                                                                                                                                                                                        |
|------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------|------------------------------------------------------------------------------------------|-----------------------------------------------------------|--------------------------------------------------------|-------------|-------------|------------------|----------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Wire Bond Pull - WBP                                 | Mil. Std. 883-2011                                                                                                                                                                                    |                                                                         |                                                                                          | 5                                                         | 0                                                      | 1           | 5           | 0 fails after TC | 5              | 30 bonds from a min. 5 devices.<br><br>Condition C or D. For Au wire diameter >=1mil, minimum pull strength after TC = 3 grams. For Au wire diameter <1mil, refer to Figure 2011-1 in MIL-STD-883 Method 2011 as a guideline for minimum pull strength. For Au wire diameter <1mil, wire bond pull shall be performed with the hook over the ball bond and not at mid-wire. |
| Wire Bond Shear - WBS                                | CDF/AEC-Q100-001                                                                                                                                                                                      |                                                                         |                                                                                          | 5                                                         | 0                                                      | 1           | 5           | 0                | 5              | 30 bonds from a min. 5 devices.                                                                                                                                                                                                                                                                                                                                             |
| External Visual                                      | Mil. Std. 883-2009/2010                                                                                                                                                                               |                                                                         |                                                                                          | All devices prior to submission for qualification testing | 0                                                      | 3           | ALL         | 0                | 5              |                                                                                                                                                                                                                                                                                                                                                                             |
| HTSL (High Temp Storage Life)                        | JESD22-A103<br>+175°C                                                                                                                                                                                 | Grade 1: 500 hrs (+175°C)                                               | Grade 1: +25°C, +85°C, +125°C                                                            | 45                                                        | 5                                                      | 1           | 50          | 0                | 21 - 83        | Spares should be properly identified.                                                                                                                                                                                                                                                                                                                                       |
| Preconditioning - Required for surface mount devices | J-STD-020<br>JESD22-A113<br><br>+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type.<br><br>MSL-1 @260C° |                                                                         | Grade 1: +25°C, +85°C, +125°C                                                            | 231                                                       | 15                                                     | 3           | 738         | 0                | 15             | Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test. 45 parts from one lot to be used for PTC test (for devices requiring PTC).                                                                                                                                                                                        |
| HAST                                                 | JESD22-A101 or A110<br><br>+130°C/85% RH for 96 hrs                                                                                                                                                   | Grade 1: 96 hrs (+130°C/85% RH)                                         | Grade 1: +25°C, +85°C, +125°C                                                            | 77                                                        | 5                                                      | 3           | 246         | 0                | 10 - 14        | Spares should be properly identified.<br>Use the parts which have gone through Pre-conditioning.                                                                                                                                                                                                                                                                            |
| UHAST                                                | JESD22-A102, A118, or A101<br><br>+130°C/85% RH for 96 hrs                                                                                                                                            | Grade 1: 96 hrs (+130°C/85% RH)                                         | Grade 1: +25°C                                                                           | 77                                                        | 5                                                      | 3           | 246         | 0                | 10             | Spares should be properly identified.<br>Use the parts which have gone through Pre-conditioning.                                                                                                                                                                                                                                                                            |
| Temp Cycle                                           | JESD22-A104<br><br>-55°C to +150°C                                                                                                                                                                    | Grade 1: 1000 cycles (-55°C to +150°C)                                  | Grade 1: +25°C, +85°C, +125°C                                                            | 77                                                        | 5                                                      | 3           | 246         | 0                | 15 - 60        | Spares should be properly identified.<br>Use the parts which have gone through Pre-conditioning.                                                                                                                                                                                                                                                                            |

# Eliminating PFAS from Microchip ICs



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SMART | CONNECTED | SECURE

**Microchip**  
August 2025

# Eliminating PFAS from MCHP ICs

- **What is PFAS**
- **Microchip's Environmental Stewardship**
- **Microchip Products with PFAS**
- **Time Frame to PFAS-Free Die Attach**
- **What is Die Attach**
- **Will clients be required to switch to PFAS free products**
- **Risk Assessment**

# What is PFAS: Poly(Per) FluoroAlkyL Substances (**PFAS**)

## Poly(Per) FluoroAlkyL Substances (PFAS)

- There may be 12,000 or more PFAS chemicals that are used in small amounts in many different items
  - PFAS can be in the product itself.
  - PFAS can also be used to manufacture products while not in the product itself

## PFAS is the new “buzzword” throughout many industries

- Often nicknamed “forever chemicals” because once released into the environment, it never degrades and will accumulate over time
- As PFAS accumulates in the environment over long periods of time, there can be increasing toxicity and polluting effects
- Therefore, government agencies around the globe are considering legislation toward removal of PFAS although PFAS legislations are not fully defined yet

# Microchip's Environmental Stewardship

Although very few laws have been enacted regarding PFAS to date, there is a rapidly growing movement among governments around the world to eliminate PFAS

- Initial legislation has targeted on clothing and food products
- Additional legislation and their timings continue to evolving

Companies such as Microchip, which are committed to addressing contaminants in water, air, food, and living organisms, are proactively working to remove PFAS even in the absence of specific legal requirements.

Microchip's suppliers are also taking proactive steps to eliminate PFAS chemicals from the materials they provide to Microchip.

Microchip believes it is prudent to take immediate action toward offering PFAS-free products to all clients, regardless of application, industry, country, or current regulatory requirements.

**Achieving “PFAS-Free” status may serve as a competitive advantage for both Microchip and its clients.**

# Microchip products with PFAS

The primary material in Microchip products containing PFAS is known as die attach. PFAS-free die attach is not new to either Microchip or the industry; in fact, Microchip has shipped hundreds of millions of units utilizing PFAS-free die attach.

Both PFAS and PFAS-free die attach materials are currently in use because PFAS was not previously identified as a substance of concern.

The change announced in this Product Change Notification (PCN) for Microchip-owned factories involves transitioning to the same PFAS-free die attach that has already been qualified and used in other products.

# Time Frame to PFAS-Free Die Attach

Qualification of products assembled at Microchip-owned factories has been completed.

While inventory containing PFAS die attach will continue to be shipped, the implementation of PFAS-free die attach in the assembly process is scheduled to begin as early as September 3, 2025.

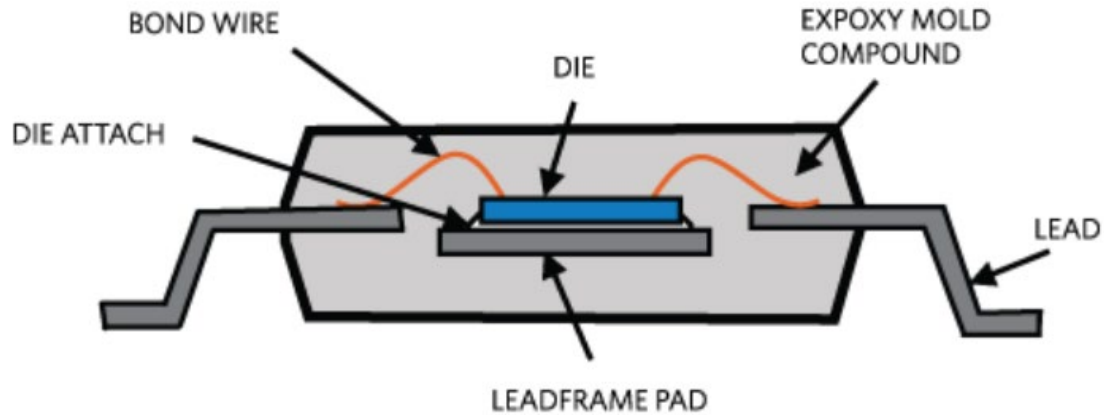
Microchip will consume all existing inventory and die attach, so the exact implementation date will depend on when current inventories are depleted.

- For PPAP clients IMDS/CAMDS material content declarations will be updated.

Schedules for assembly locations not owned by Microchip (subcontractors or "subcons") are currently under review. We anticipate a similar mix of products already utilizing both PFAS and PFAS-free die attach at these locations.

Product Change Notifications (PCNs) announcing die attach changes at subcontractor sites will be issued once schedules are finalized. We expect these timelines to be similar to those for our internal factories.

# What is die attach



**A thin layer of epoxy between the silicon die and copper pad portion of the lead frame.**

- Holds the die in place during the wire bond and mold encapsulation processes
- The bottom of the die has no transistors or active circuits.
- The interface is identical regardless of device type, fab location, technology node, wire material etc.
- **Therefore, allows extremely broad range of products to be grouped into a single qualification.**

# Will Clients be required to switch to PFAS-Free Products

The timeline for legislation to eliminate PFAS chemicals remains uncertain; however, regulatory action is anticipated.

Suppliers of PFAS chemicals and raw materials containing PFAS are already announcing end-of-life plans in advance of any formal legislation.

It is expected that suppliers will discontinue offering die attach materials containing PFAS within the next two years, regardless of when government regulations take effect.

While Microchip is committed to providing as much transition time as possible for our clients, we strongly encourage you to begin planning now to avoid potential supply interruptions.

# Risk Assessment:



Microchip does not anticipate that this change will impact our clients for the following reasons:

- Microchip has been using PFAS-free die attach material for several years.
- We have shipped hundreds of millions of units utilizing this material without incident.
- Die Attach is not application relevant.

Given these factors, Microchip believes there is minimal cause for concern regarding this change, and additional client qualifications would be redundant and time-consuming. However, if you have any questions that are not addressed in the PCN or this presentation, please do not hesitate to contact us.

